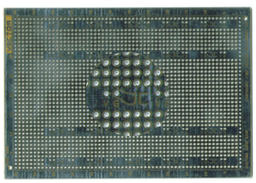
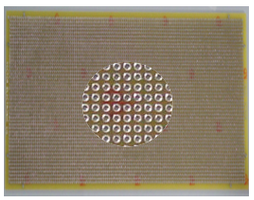
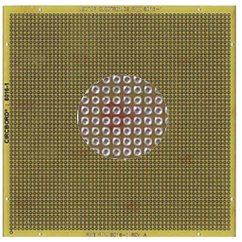
Round Pads-Per-Hole with 0.042” Holes, .100” Grid



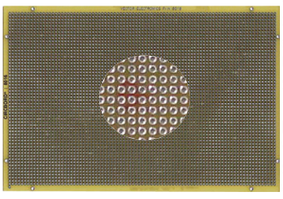
8008 4.5”Hx6.5”L x .062” TH
0.100” grid, UNIQUE circuit pattern features full voltage and ground planes on both sides with isolated plated-thru holes. 0.080” solder pads and Surface Mount cap positions for discreet decoupling capacitors. Solder coated pattern.
Material: FR4
WW Terminals: T44, T46, T49, T68
Solder Terminals: T42-1
WW Socket Pin: R32



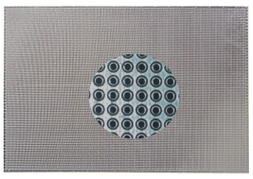
8006 5.0”Hx13.25”L x.062” TH
0.100” grid Pad-Per-Hole Pattern copper plated-thru holes both sides .042” holes with .080” isolated solder pad around each hole on both sides
16-Pin DIP= 154
Material: FR4 Epoxy Glass
WW Terminals: T44, T46, T49, T68
Solder Terminals: T42-1
WW Socket Pin: R32



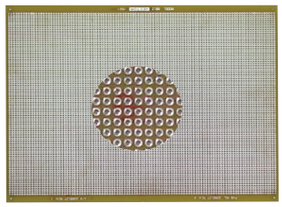
8016-1 6.0”H x 6.0”L x .062” TH
0.100” grid Pad-Per-Hole Pattern on one side only, 0.042” holes
Small economical size.
Solder coated pattern
Material: FR4
WW Terminals: T44, T46, T49, T68
Solder Terminals: T42-1
WW Socket Pin: R32



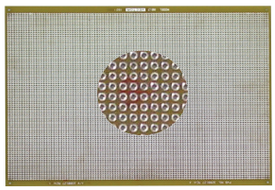
8016 6.0”H x 9.0”L x .062” TH
0.100” grid Pad-Per-Hole Pattern on both sides, 0.042” holes plated-thru copper. Unrestricted component placement.
Solder coated pattern
16-Pin DIP capacity = 165
Material: FR4
WW Terminals: T44, T46, T49, T68
Solder Terminals: T42-1
WW Socket Pin: R32



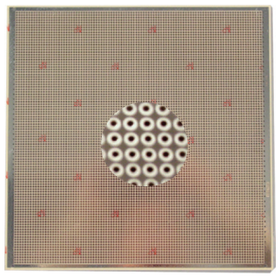
106P70-4 7.0”H x 10.6”L x.062”TH
0.100” grid Pad-Per-Hole Pattern on both sides. Etched ground plane surrounds 0.080” pads on both sides. 0.042” holes plated-thru copper. Solder coated pattern.
16-Pin DIP= 175
Material: FR4
WW Terminals: T44, T46, T49, T68
Solder Terminals: T42-1
WW Socket Pin: R32



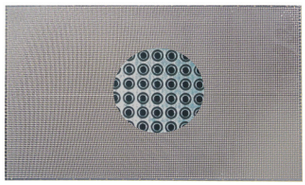
8012 9.2”Hx11.0”L x .062” TH
0.100” grid Pad-Per-Hole Pattern. .042” holes plated thru with .080” isolated solder pad around each hole on both sides.
16-Pin DIP= 72.
Material: FR4.
WW Terminals: T44, T46, T49, T68.
Solder Terminals: T42-1, K24C
WW Socket Pin: R32



8013 10.5”Hx18.0”L x .062” TH
0.100” grid Pad-Per-Hole Pattern on both sides. Isolated 0.080” pads with 0.042” holes plated-thru copper. Unrestricted component placement.
Solder coated pattern
16-Pin DIP= 175
Material: FR4.
WW Terminals: T44, T46, T49, T68.
Solder Terminals: T42-1
WW Socket Pin: R32

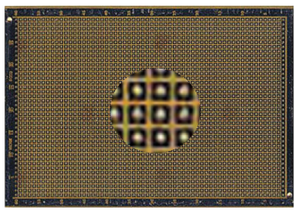


106P106-1 10.6”Hx10.6”L .062”TH
0.100” grid Pad-Per-Hole & peripheral Ground Plane on both sides .042” holes not plated thru with .080” isolated solder pad around each hole
16-Pin DIP= 275
Material: CEM-1
WW Terminals: T44, T46, T49, T68
Solder Terminals: T42-1
WW Socket Pin: R32



106P180-4 10.5”Hx18.0”Lx.062”TH
0.100” grid Pad-Per-Hole Pattern on both sides. Etched ground plane surrounds 0.080” pads on both sides. 0.042” holes plated-thru copper. Unrestricted component placement.
Solder coated pattern.
16-Pin DIP = 175
Material: FR-4
WW Terminals: T44,T 46, T49, T68
Solder Terminals: T42-1
WW Socket Pin: R32

Square Pads-Per-Hole with 0.042” Holes, .100” Grid



8003 4.50”Hx6.50”L x.062” TH
0.100” grid Pad-Per-Hole Pattern & peripheral Ground Plane on one side only
Single-sided with no etch & plating on reverse side .042” holes not plated thru
.085” square isolated solder pad
16-Pin DIP= 60
Material: CEM-1
WW Terminals: T44, T46, T49, T68
Solder Terminals: T42-1
WW Socket Pin: R32